

[METHOD FOR DEPOSITING THIN FILM USING PLASMA CHEMICAL VAPOR DEPOSITION]

Abstract of Disclosure

A thin film deposition method using plasma enhanced chemical vapor deposition is described. In a plasma enhanced chemical vapor deposition chamber, plasma is used to enhance the chemical reaction to form a thin film on a substrate. The substrate is then removed, followed by passing a cleaning gas into the chamber to remove residues in the chamber. Before loading another batch of substrate in the chamber, a pre-deposition process is performed to isolate contaminants generated from the cleaning process. A discharge plasma treatment is then conducted to lower the amount of accumulated electrical charges.

Figures